

## ABSTRACT

A device and a system for cooling heat generating electronics is disclosed. In one embodiment, the invention is a system for cooling at least one computer component. The system has a plurality of cold plates which are adapted to transfer heat from a plurality of computer components to a cooling fluid. A supply line supplies the cooling fluid to and from these cold plates. The system also has a housing with one or more racks to support the computer component(s). The racks may also support the cold plates so that the cold plates are in thermal communication with at least one computer component.

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